SEVENTH FRAMEWORK PROGRAMME

Cluster-based Innovation through Embedded Systems technology

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Author(s):	**Cristina Urtiaga and Cristina Murillo**
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Abstract:

This deliverable presents the activity developed during the Embedded World Fair in February 2016 as well as a short list of the Smart City Events visited by the partners.

Keyword list:

Fair, Show, Workshops

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1   Executive Summary

The present document is a deliverable of the CLINES project, funded by the European Commission under FP7.

The report D.7.6 is a public document that summarises the consortium participation on the Embedded World Fair during the month of February that has been attended with the aim of promoting the project activities and results, and fostering its exploitation potential. As well as a resume of Smart City events participated by the members.

This is a new deliverable not foreseen in our first proposal but introduced in the amendment request recently submitted to the European Commission.

2   The Fair

The Embedded world fair is the leading international show for embedded systems and it is the place to discover the innovations from the embedded sector, as well as the place to contact with companies and stakeholders in this domain, and for these reasons the CLINES partners consider it as a good showcase for the project.

The fair was held from 23-25 February 2016 in Nuremberg, Germany.

The fair occupied more than 4 pavilions with 939 exhibitors and around 30,000 visitors, from 38 different countries, this trade fair is becoming The Event to attend in the field of embedded systems.

A walk through the different halls gave inspiration for a description of some of the highlights of the fair: a novelty in this years' edition was the specific focus on security and safety. Issues like: "How do I protect my embedded system from an attack?", "How do I design tamper-proof software?", "What to do against piracy?" etc. were tackled in a specific area of the exhibition grounds.

The most important topic however, being the topic everyone talked about, a topic that was at least mentioned three times on almost every booth this year was IoT − Internet of Things. Be it IoT or Industry 4.0 or a "Connected World", every booth had at least one desk with an info stand on connected devices and cloud applications. Some companies provide small, low-end but connected sensor devices while other organizations focus on the software or the cloud services. Most of the time sensors are built in some kind of a sensor module where, next to the sensor itself, there is also some logic or processing unit to do the first data processing. A communication chip (Zigbee, Sigfox, LoRa, Wifi, BLE, etc.) often completes the sensing module. And as conclusion, IoT is definitely here to stay!
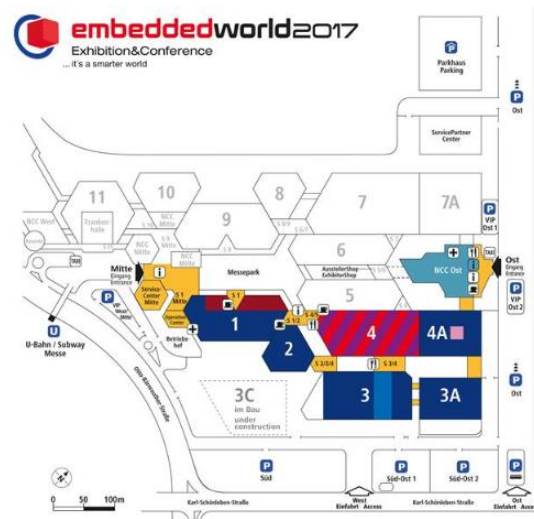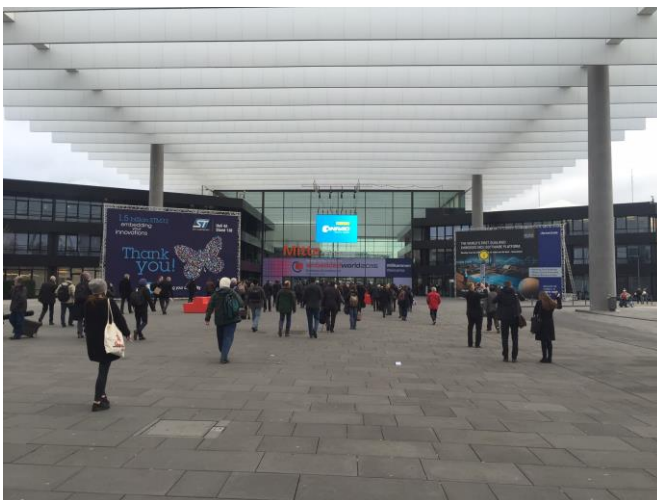

The booth of CLINES was located in pavilion four in a main corridor where the flow of people was quite abundant and in a space that offers high visibility. That circumstance allows us to attend people who were interested in our initiative.
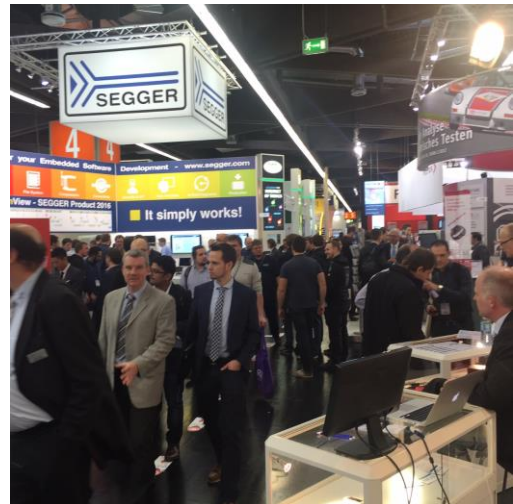
The booth of CLINES also had an additional advantage of sharing a common space with companies of our partner in the DSP Valley project who were the first to know the activities and results of the project.
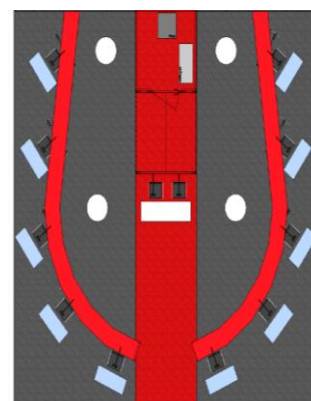
3   Objectives

The CLINES partners decide that the Embedded World fair was an interesting opportunity and therefore plan to actively participate with the following objectives:

- Make visible the project and the work developed

- Know, visit and explore the fair to meet the present and future technological trends exposed

- Encourage collaboration between project companies and visitors to the fair

- Identify and promote new opportunities for collaboration

- Foster collaboration among member companies of the cluster project

- Expand the network of collaborators in the field of Smart Cities

4   Embedded World Visibility Actions

An information poster of the project was designed for the event and was placed at the booth and its aim was to draw the attention of visitors and encourage them to interact with the project partners.

CLINES and general introduction brochures were also placed in the booth to serve as a guiding thread and visual support with explanations of the project.

The Cluster partners of the project actively participated in the fair and shared the stand and interacted with the visitors.

Lastly, we may state that several communiqués to inform our partners about our participation in the fair, as well as a press release were made and information was retweeted on social networks.

CLiNES

LOS MIEMBROS DEL PROYECTO CLINES PARTICIPAN EN LA MAYOR FERIA DE SISTEMAS EMBEBIDOS DE EUROPA

El Consorcio para el desarrollo de la industria europea de los sistemas embebidos orientados a las Smart Cities participa en la Conferencia Embedded World 2016 para presentar sus propuestas a uno de los mercados de mayor crecimiento en Europa

17 de febrero de 2016

Los principales proveedores de seguridad en sistemas electrónicos, inteligencia distribuida e Internet de las cosas se darán cita en Nuremberg los días 23 a 25 de febrero en la Embedded World Conference, la principal cita de la industria europea. Los miembros del Proyecto Clines participarán en la Feria con un una presencia propia, y expondrá a los principales agentes industriales las líneas de trabajo a través de las cuales trabaja para posicionar a Europa en el mercado mundial de las soluciones para la creciente urbanización del mundo.

Clines es un consorcio formado por cuatro grandes agrupaciones empresariales y tecnológicas europeas (Clusters) en representación del sector TEIC vasco y español. Gaia participa en él junto con DSP Valley (Bélgica). BICCnet (Alemania) y BrainsBusiness, Dinamarca. En total, los miembros de este proyecto representan a más de 1.000 organizaciones (desde la industria hasta la Academia), principalmente pequeñas y medianas empresas, y representan más de 60.000 profesionales.

La Embedded World Conference es una de las citas más destacadas en Europa sobre sistemas electrónicos e inteligencia distribuida. Además de ofrecer un mercado de intercambio comercial y de experiencias, la Conferencia actúa como punto de revisión de las principales tendencias en un mercado en constante crecimiento.

La creciente urbanización de las ciudades y el desarrollo de servicios que requiere es una tendencia imparable en todo el mundo. Según las estimaciones, en 2040 el 65% de la población mundial residirá en entornos urbanos, y esta tendencia acrecentará la necesidad de todo tipo de soluciones para garantizar un nivel de calidad de vida digno, que implica servicios y soluciones en todos los ámbitos: personas, entornos, movilidad, gobernanza, nueva economía, etc.

Ven y visítanos en nuestro stand en el Hall 4, booth nr. 140

PAÍS VASCO

El 88% del nuevo empleo cubrirá jubilaciones en Euskadi hasta 2024

Urkullu: "No es recomendable repetir elecciones"

Clines Project @ClinesProject · 26 abr.
Encuentro @SmartCity_Tech en Donostia cc @grupospri @expansioncom @Tecnologiavasca ow.ly/4n2jEP @EU_Commission
♥ 1

Clines Project @ClinesProject · 25 abr.
April 27th. San Sebastian. ow.ly/4mZwfx Workshop on groundbreaking ideas and solutions for smartcities. cc @grupospri
♺ 1

Clines Project @ClinesProject · 25 abr.
Ready to meet in San Sebastian? ow.ly/4mZuFf cc @ClusterGaia @tecnalia@BrainsBusiness1 #BICCNet @DSPValley #IWT #CISS
♺ 1

Clines Project @ClinesProject · 24 abr.
The Members of CLINES Participate in Embedded World - THE MEMBERS OF THE CLINES PROJECT PARTICIPATE IN EUROPE'S... ow.ly/8JGezS

5   Smart City Events

Similarly, throughout the project life the partners have participated in other fairs, congress and workshops in order to promote the project objectives and activities.

We list below a summary of the most important ones:

Partner meetings:

- Kick-off meeting in Aalborg, Denmark (Aalborg), 24 October 2013

- General Assembly meeting in Leuven (Belgium), Belgium, 6-8 March 2014

- General Assembly meeting in Bilbao (Spain), Spain, 9-10 February 2015

- General Assembly meeting in Aalborg (Denmark), 9 June 2015

- General Assembly meeting in San Sebastian (Spain), 25 April 2016

CLINES workshops:

- 1st Innovation Workshop in Leuven (Belgium),13 June 2014

- 2nd Innovation Workshop in Aalborg (Denmark), 8 June 2015

- 3nd Innovation Workshop in Munich (Germany), 28 October 2015

- 4th Innovation Workshop in San Sebastian (Spain), 27 April 2015

Other CLINES meetings:

- CLINES regional interest group meeting in Elgoibar (Spain) on 26 November 2013

- CLINES regional interest group meeting in Ermua (Spain) on 4 April 2014

- CLINES regional interest group meeting in Aalborg (Denmark) on 25 August 2014

- Internal CLINES Innovation Workshop dryrun in Aalborg (Denmark), 15-16 September 2014

- Kick-off CLINES Regional Interest Group meeting, Munich (Germany) on 25 November 2014

- CLINES Regional Interest Group meeting at company Osram, Munich (Germany) on 3 February 2015

- CLINES regional interest group meeting in Elgoibar (Spain) on 12 February 2015

- CLINES strategy meeting in Brussels (Belgium), 9 January 2015

- Innovation workshop coaching in Munich (Germany), 22 September 2015

- CLINES regional interest group meeting in Bilbao (Spain) on 21 October 2015

- CLINES regional interest group meeting in San Sebastian (Spain) on 10 February 2016

Other events with participation from CLINES partners:

- DSP Valley's Smart Systems Industry Summit – SSIS 13' in Mechelen (Belgium) 4 December 2013

- Regions of Knowledge workshop in Brussels (Belgium), 10-12 December 2013

- Agoria Smart Cities Forum in Brussels (Belgium) on 29 January 2014

- Embedded World Exhibition and Conference in Nuremberg (Germany) 24-26 February 2014

- Cluster-to-Cluster Conference and Matchmaking (Berlin) on 18-19 September 2014

- DSP Valley's Smart Systems Industry Summit – SSIS 14' in Mechelen (Belgium) 14 October 2014

- CLINES-Booth at the EuroCities conference, Munich (Germany), 5-7 November 2014

- Smart City Expo in Barcelona (Spain) on 18-20 November 2014

- Embedded World Exhibition and Conference in Nuremberg (Germany) on 24-26 February 2015

- BICC Innovation Forum Digitalisierung, Munich (Germany) on April 21 2015, with meeting of CLINES Regional Interest Group, and speech by St. Sebastian town official

- International Congress in Digital Cities in Santiago de Cospostela (Spain) on 21-22 April 2015

- International Congress in Digital Cities Smart Solutions for Cities Presentations ; Bilbao (Spain) on 23 April 2015

- CLINES Regional Interest Group meeting at Municipality of Munich (Germany) on July 2nd 2015

- Cluster-to-Cluster Conference and Matchmaking (Copenhagen) on 17-18 September 2015

- Smart City Expo of Barcelona (Spain) on 17-19 October 2015

- Embedded World Exhibition and Conference in Nuremberg (Germany) on 24-26 February 2016

- European Sustainable Cities 8th Congress in Bilbao (Spain) on 27-29 April 2016